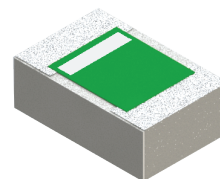


RZ0805ZZ-XXXXJN-98 Features:

- Wraparound One Extended Pad Configuration
- Solder Attachment
- Customer Defined Testing Available
- RoHS Compliant or Sn62
- Tape & Reel or Waffle Pack Available (Standard is bulk)
- 5% Resistor Tolerance

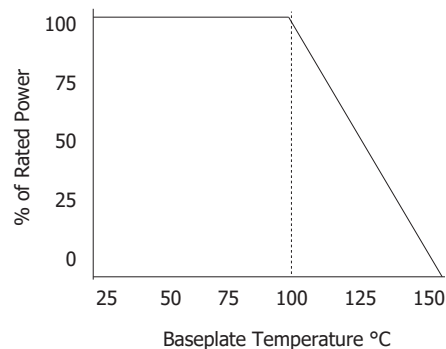


RZ0805ZZ-XXXXJN-98 Parameters:

Resistance Range:	0.5Ω - 1MΩ	
Rated Power:	5W*	
Return Loss (Typical)**:	20dB or Better	(DC - 3GHz)
	17dB or Better	(>3GHz - 4GHz)
Construction:	Thick Film on BeO	
Operating Temperature:	-55 to +150°C	

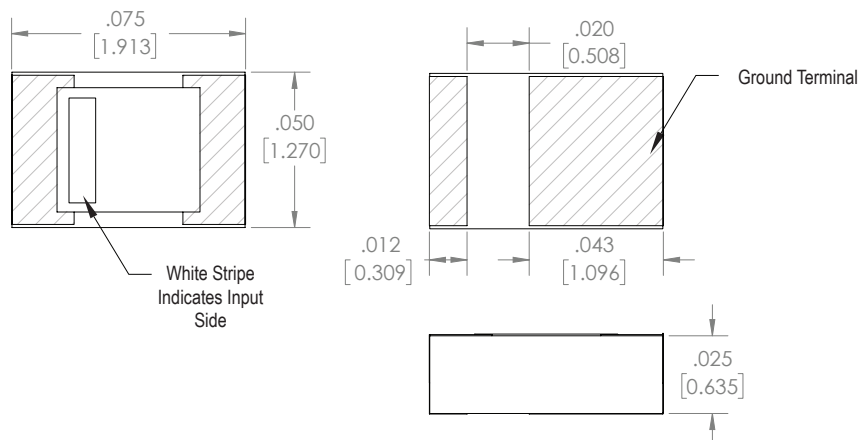
■ Actual Size

RZ0805ZZ-XXXXJN-98 Power Derating Curve



* Rating based on ≤100°C constant baseplate temperature
 ** Test performed on a 50Ω device in a matched, continuous 50Ω system with proper workmanship

RZ0805ZZ-XXXXJN-98 Dimensions:



Dimensions in inches [mm]
 Tolerance is ± 0.010 [0.254] unless otherwise stated

Ordering Information:

RZ	0805	ZZ	-	XXXX	J	N	-	98	UU
Prefix for Wraparound Resistor w/ One Extended Backpad	Size	Value Code		Tolerance	Normal Inspection	Substrate		Packaging	
	0805	50R0 - 50Ω 1000 - 100Ω 1001 - 1KΩ 1002 - 10KΩ 1003 - 100KΩ 1004 - 1MΩ		J - 5%	Contact factory for additional options	98 - 0.025" BeO		Blank - Bulk TR - Tape and Reel WP - Waffle Pack	
Terminal Metallization			RoHS	Magnetic	Solder	Epoxy	Wirebond		
AS - Tin Lead over Platinum Palladium Gold			No	No	Yes	No	No		
CB - Tin Lead over Nickel over Silver			No	Yes	Yes	No	No		
CT - 100% Matte Tin over Nickel over Silver			Yes	Yes	Yes	No	No		

Barry Industries reserves the right to change part number and/or process without notification.

RZ0805ZZ-XXXXJN-98 Reliability Specifications:

Parameter:	Test Condition:	Results:
Short Time Overload	Apply 1.1x Rated Power for 5 Seconds.	≤ 5.0% Resistance Shift
Rated Load Life	Apply 1/2 Power Under 40°C ±2°C 90 Minutes on/ 30 Minutes off. Repeat for 100 hours	≤ 5.0% Resistance Shift
Moisture Resistance	MIL-PRF-55342 para 4.8.9 95% RH, 25°C - 65°C	≤ 5.0% Resistance Shift
Resistance to Soldering Heat	MIL-STD-202 Method 210 and MIL-PRF-55342 Para 4.8.8.1	≤ 5.0% Resistance Shift
Resistance to Bonding Exposure	MIL-PRF-55342 Para 4.8.8.2	≤ 5.0% Resistance Shift
Solderability	MIL-PRF-55342 Para 4.8.12	>95% Covered
High Temperature Storage	125°C ±2°C for 500 Hours	1.) ≤ 5.0% Resistance Shift 2.) No Significant Abnormality (Visual)
Thermal Shock	-65°C to +150°C 30 Minutes Dwell, 5 Cycles	1.) ≤ 5.0% Resistance Shift 2.) No Significant Abnormality (Visual)

Barry Industries reserves the right to change part number and/or process without notification.